



BAP50-04

General purpose PIN diode

Rev. 3 — 26 November 2018

Product data sheet

1 Product profile

1.1 General description

Two planar PIN diodes in series configuration in an SOT23 small plastic SMD package.

1.2 Features and benefits

- Two elements in series configuration in a small-sized plastic SMD package
- Low diode capacitance
- Low diode forward resistance

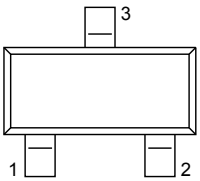
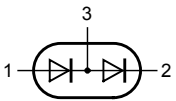
1.3 Applications

- General RF application



2 Pinning information

Table 1. Discrete pinning

Pin	Description	Simplified outline	Graphic symbol
1	anode	 <p>Top view</p>	 <p>aaa-025249</p>
2	cathode		
3	common connection		

3 Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
BAP50-04	-	plastic surface-mounted package; 3 leads	SOT23

4 Marking

Table 3. Marking code

Type number	Marking code
BAP50-04	4L%

5 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	50	V
I_F	forward current		-	50	mA
P_{tot}	total power dissipation	$T_{sp} \leq 90\text{ °C}$	-	250	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-65	+150	°C

6 Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		220	K/W

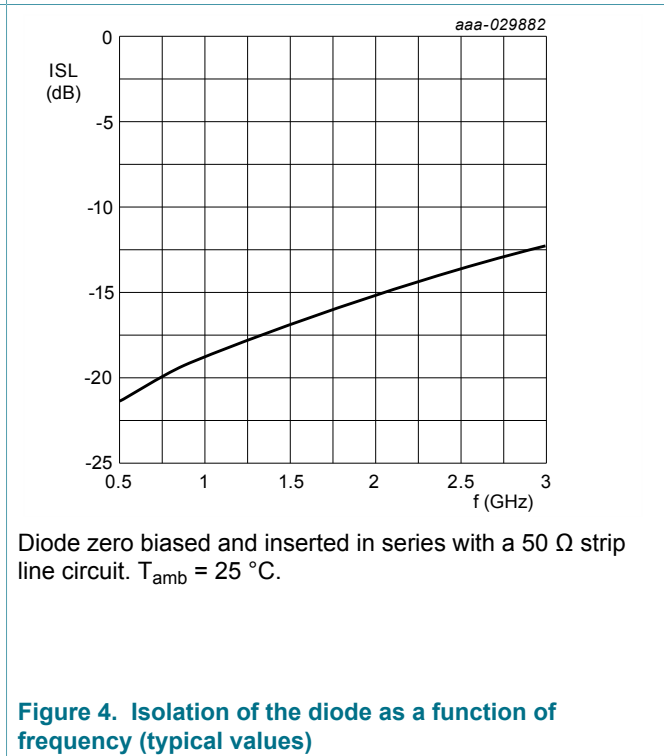
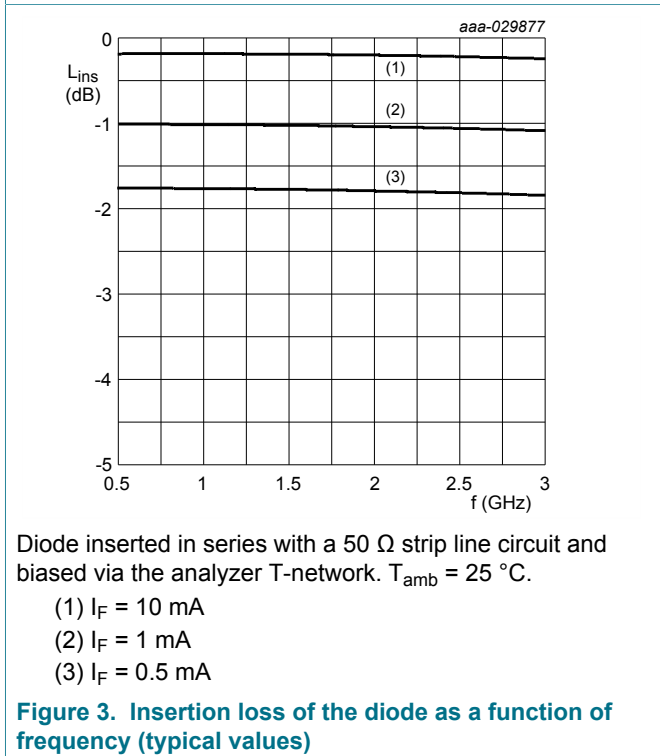
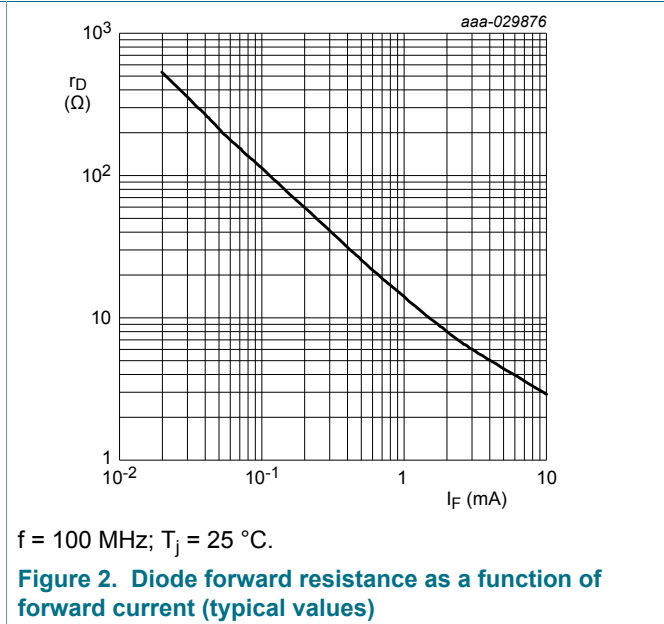
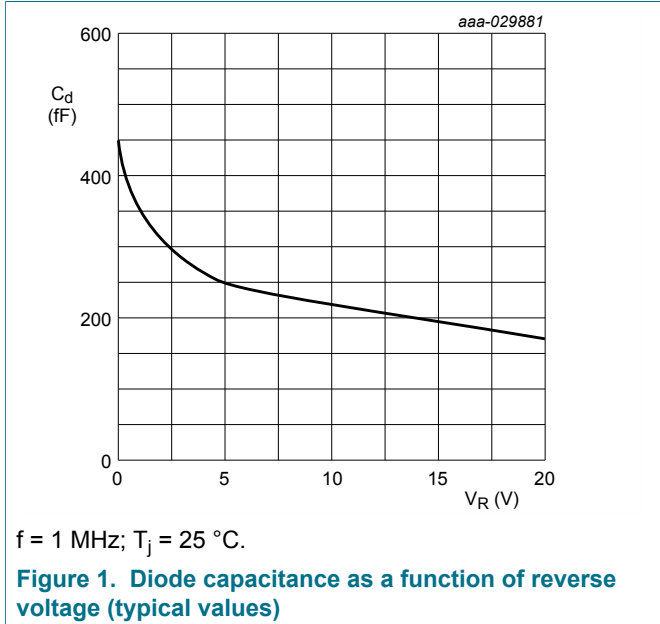
7 Characteristics

Table 6. Characteristics
T_j = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
V _F	forward voltage	I _F = 50 mA	-	0.95	1.1	V	
V _R	reverse voltage	I _R = 10 μA	50	-	-	V	
I _R	reverse current	V _R = 50 V	-	-	100	nA	
C _d	diode capacitance	f = 1 MHz (see Figure 1)					
		V _R = 0 V	-	0.45	-	pF	
		V _R = 1 V	-	0.35	0.6	pF	
		V _R = 5 V	-	0.3	0.5	pF	
r _D	diode forward resistance	f = 100 MHz (see Figure 2)					
		I _F = 0.5 mA	[1]	-	25	40	Ω
		I _F = 1 mA	[1]	-	14	25	Ω
		I _F = 10 mA	[1]	-	3	5	Ω
τ _L	charge carrier life time	when switched from I _F = 10 mA to I _R 6 mA; R _L = 100 W; measured at I _R 3 mA	-	1.05	-	μs	
L _S	series inductance		-	1.4	-	nH	

[1] Guaranteed on AQL basis: inspection level S4, AQL 1.0.

8 Graphical data



9 Package outline

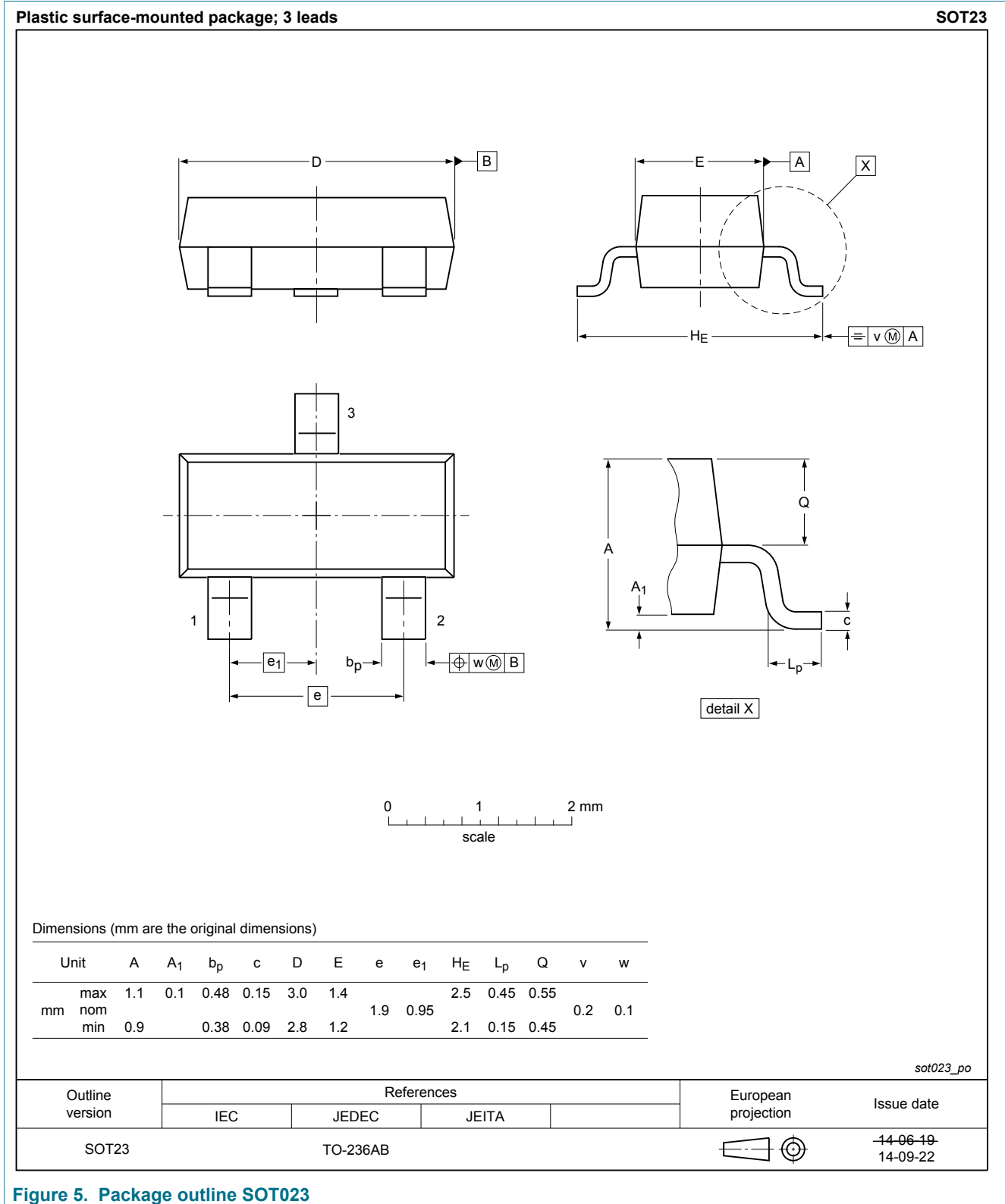


Figure 5. Package outline SOT023

10 Abbreviations

Table 7. Abbreviations

Acronym	Description
AQL	acceptable quality level
PIN	P-type, intrinsic, N-type
RF	radio frequency
S4	special inspection level 4
SMD	surface-mounted device

11 Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP50-04 v.3	20181126	Product data sheet	-	BAP50-04 v.2.1
Modifications:	<ul style="list-style-type: none">• Section 1.2 "Features and benefits" has been updated.• The "Legal information" pages have been updated.			
BAP50-04 v .2.1	19991203	Product data sheet	-	BAP50-04 v.1

12 Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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